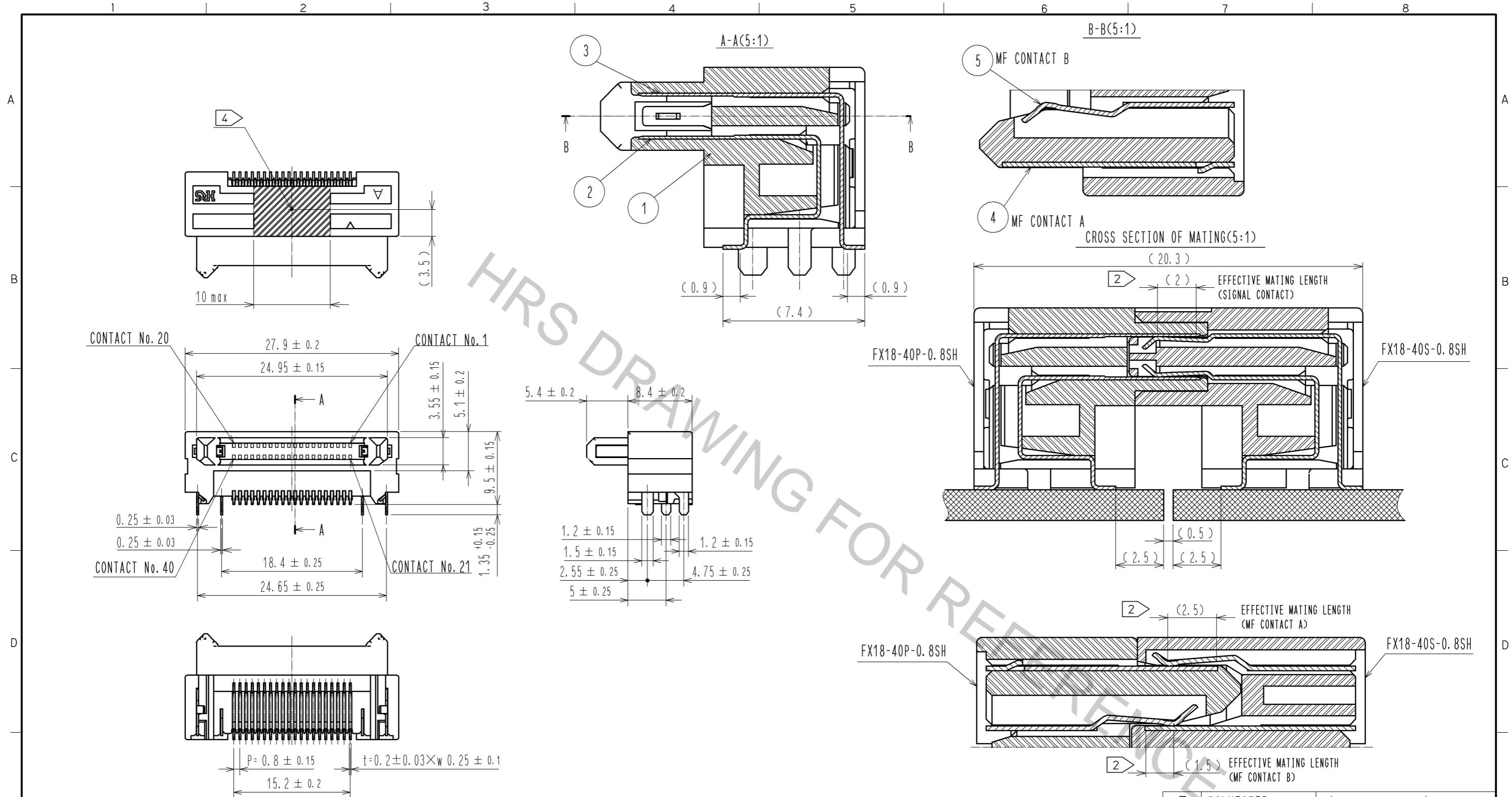


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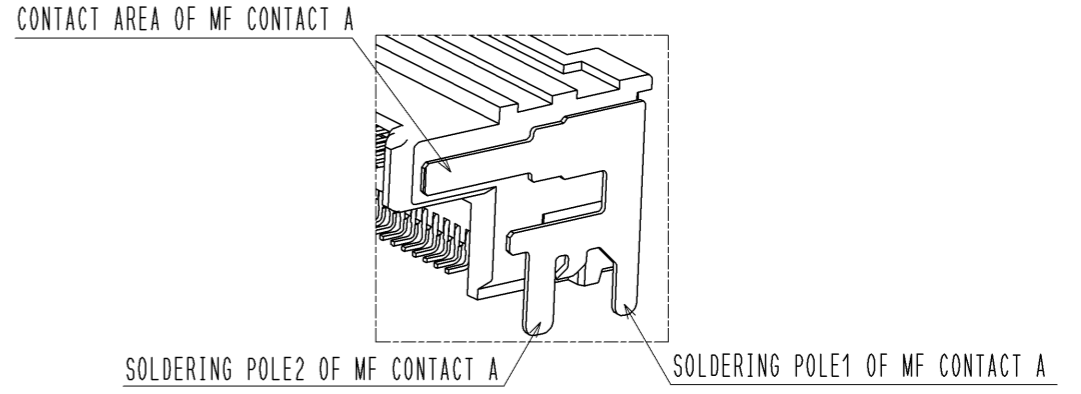
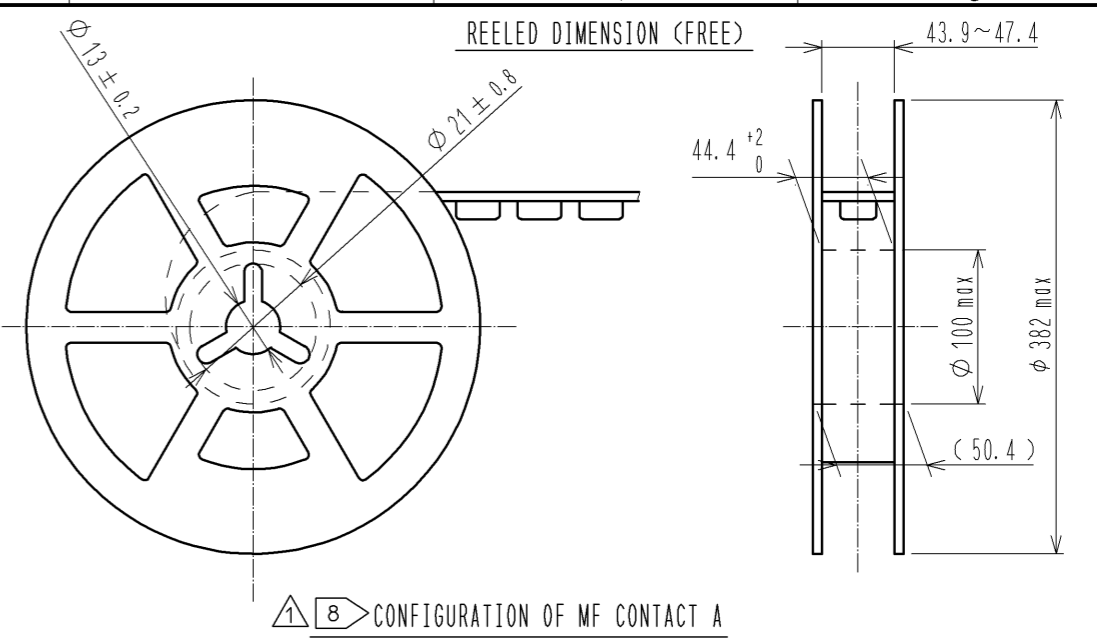
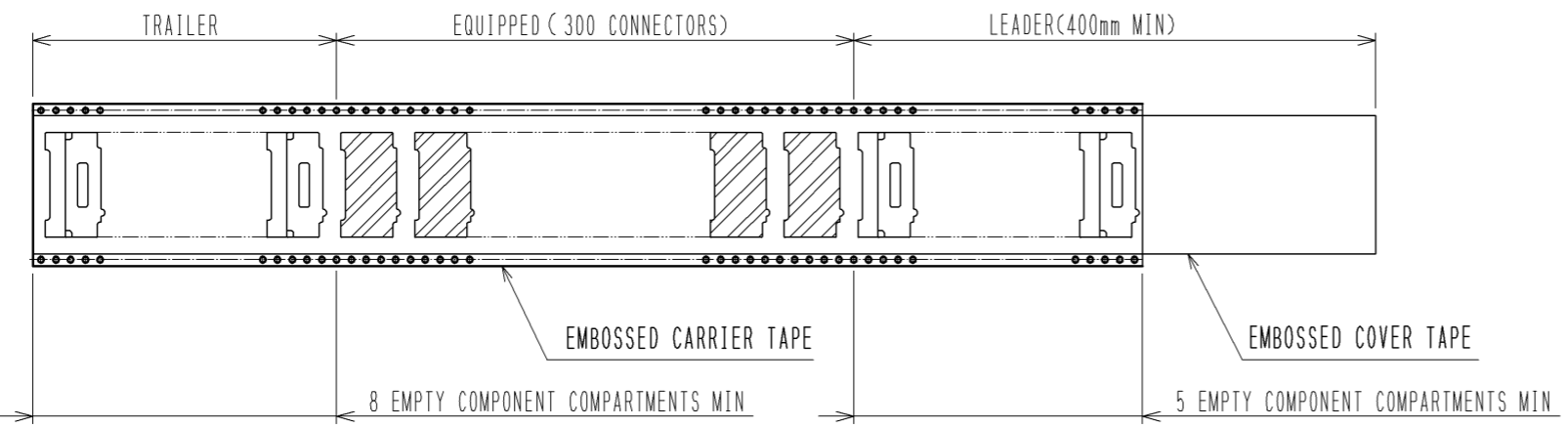
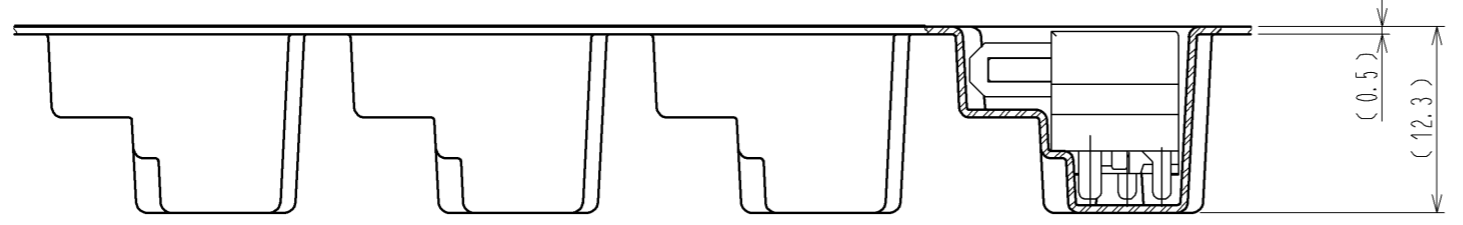
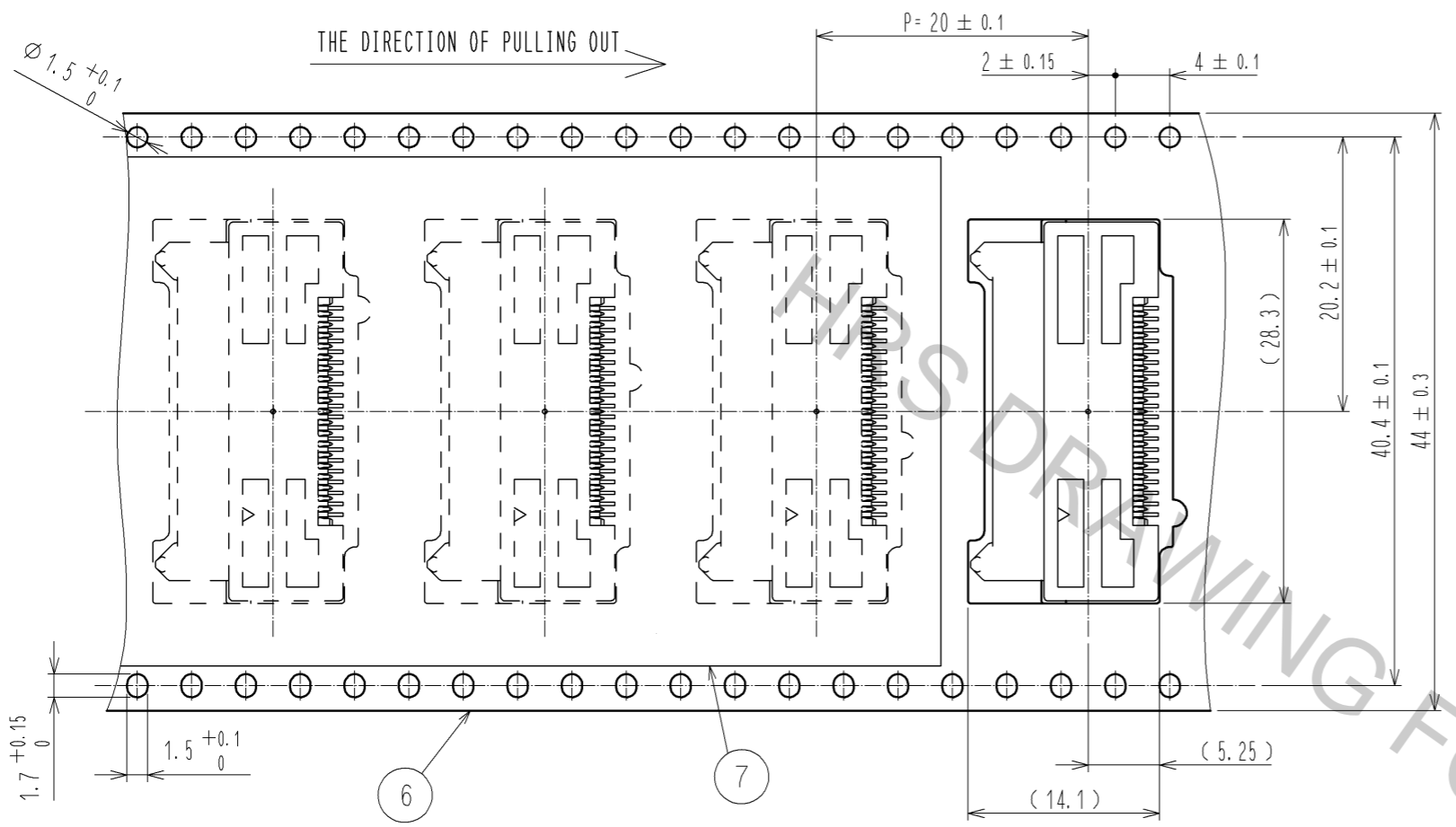
- NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.
- ② CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A->SIGNAL CONTACT->MF CONTACT B) WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
 - 3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
 - ④ IT SHOWS CONNECTOR'S CENTRE OF GRAVITY AND VACUUM PICKUP AREA.
 - ⑤ PACKING FOR PRODUCT APPLIES EMBOSSED CARRIER TAPE PACKING. (300pcs/RL)
 - 6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.
 - 7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.
 - ①⑧ SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES. BE SURE TO CONNECT TO THE SAME CIRCUIT.

NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1µm LEAD AREA:GOLD 0.03µm UNDER PLATING:NICKEL 1.3µm		7	POLYESTER		(EMBOSSD COVER TAPE)
2	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1µm LEAD AREA:GOLD 0.03µm UNDER PLATING:NICKEL 1.3µm		6	POLYSTYRENE		(EMBOSSD CARRIER TAPE)
1	POLYAMIDE	BLACK UL94V-0		5	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1µm LEAD AREA:TIN-PLATING 1µm UNDER PLATING:NICKEL 1.3µm	
				4	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1µm LEAD AREA:TIN-PLATING 1µm UNDER PLATING:NICKEL 1.3µm	

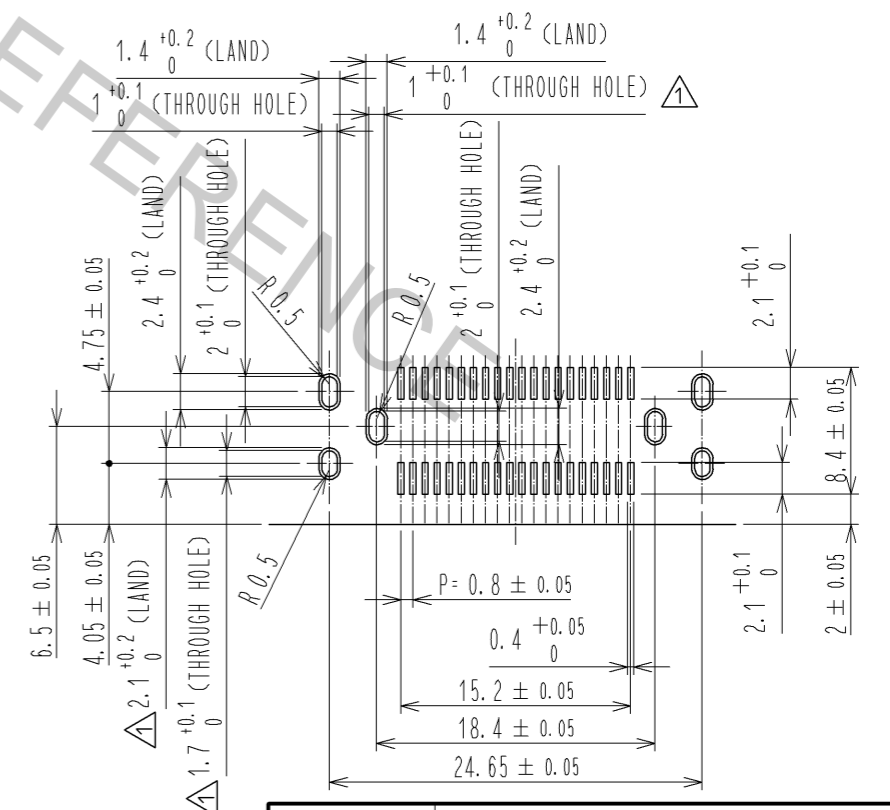
UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	2 : 1	5	DIS-F-005578	TH. SANO	KI. HIROKAWA	11.07.21

APPROVED	CHECED	DESIGNED	DRAWN	DATE	DRAWING NO.	PART NO.	CODE NO.
HS. OKAWA	KI. HIROKAWA	TH. SANO	TH. SANO	09.10.13	EDC3-159074-02	FX18-40P-0.8SH(11)	CL579-0002-5-11

5 DRAWING OF PACKING (2:1)



RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)
(PCB THICKNESS: $t=1.6\text{mm}$ METAL MASK THICKNESS: $t=0.12\text{mm}$)



HRS	図番:	EDC3-159074-02	2/2
	製品名:	FX18-40P-0.8SH(11)	
	製品コード:	CL579-0002-5-11	